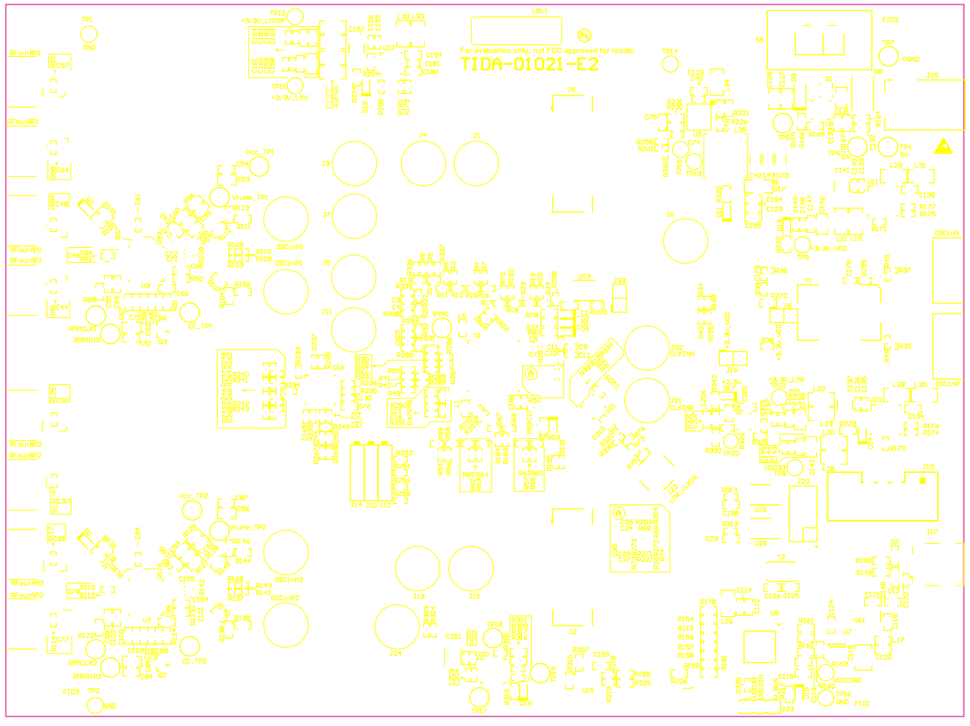
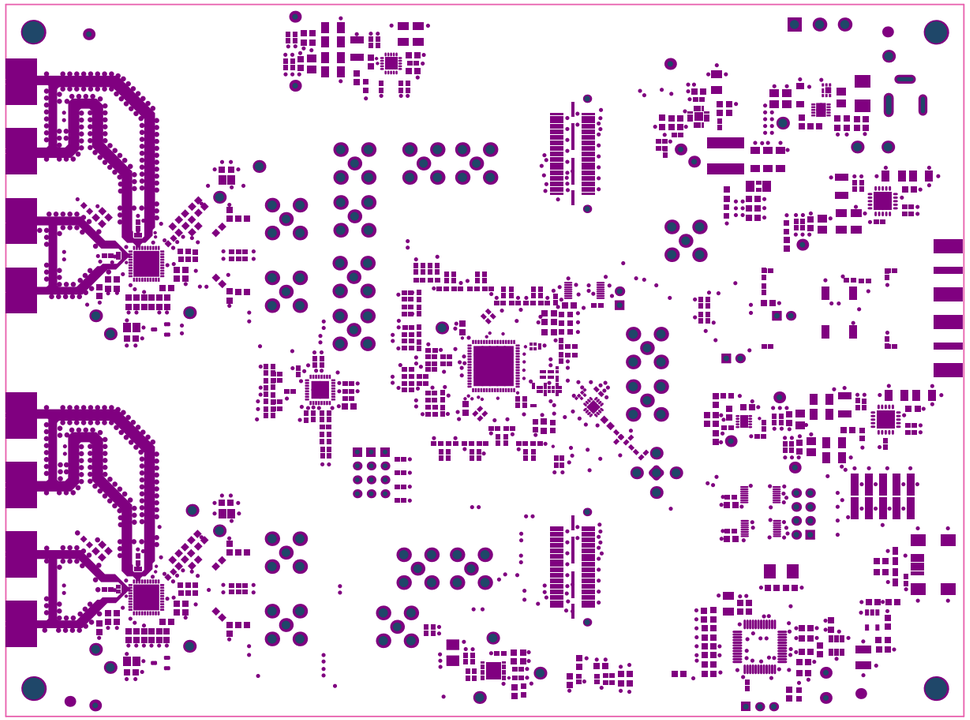
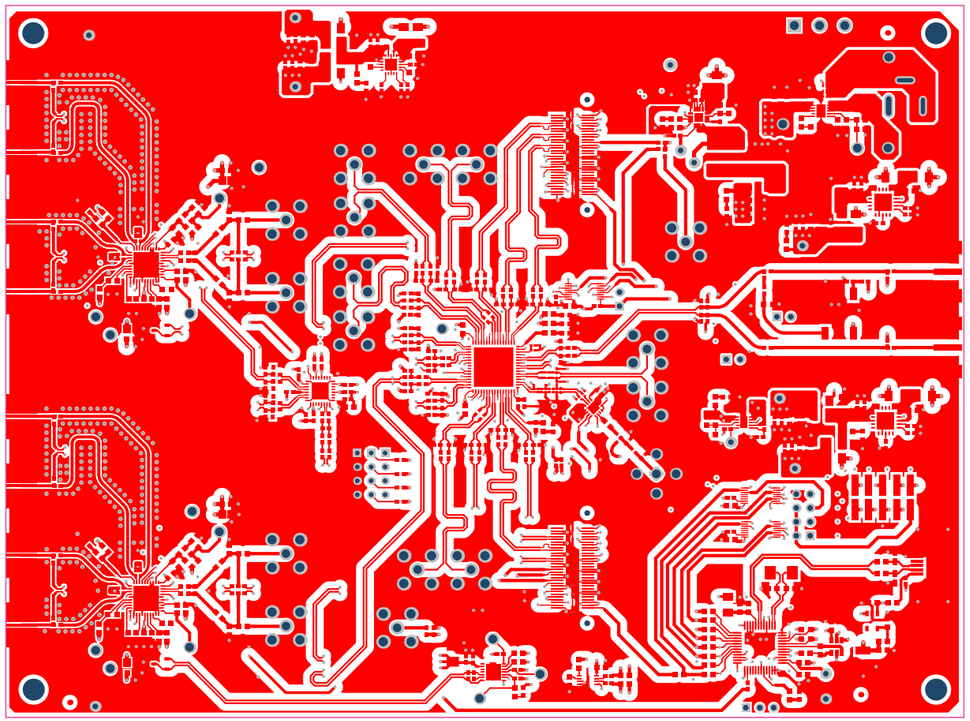


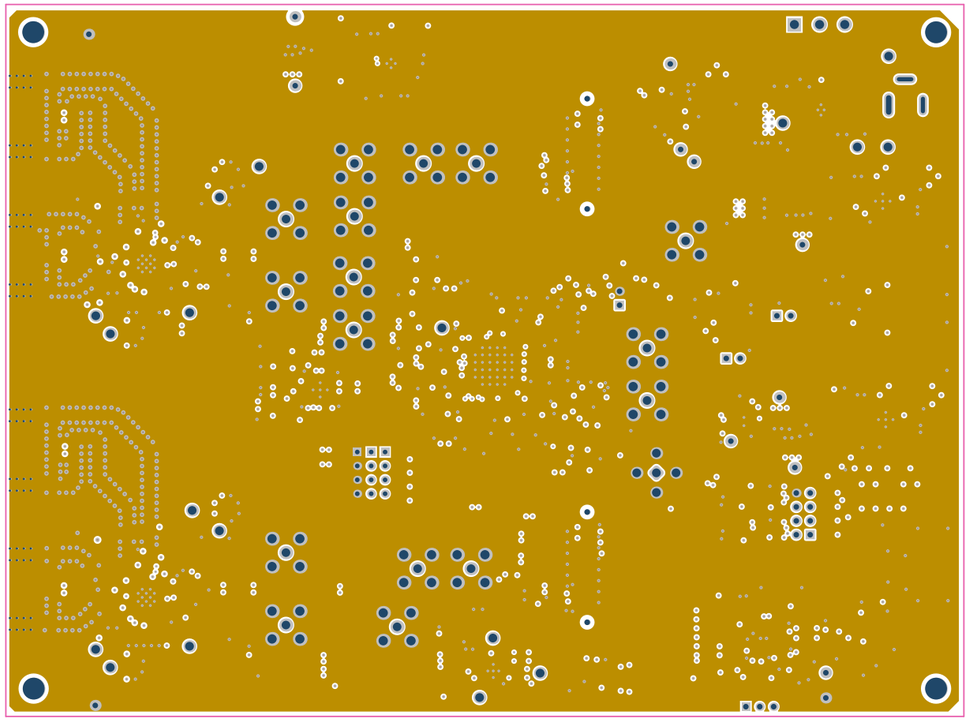
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SUN REV:
LAYER NAME = TOP OVERLAY	TID #:01021		
PLOT NAME = Top Overlay	GENERATED : 10/13/2017 5:38:46 PM		TEXAS INSTRUMENTS



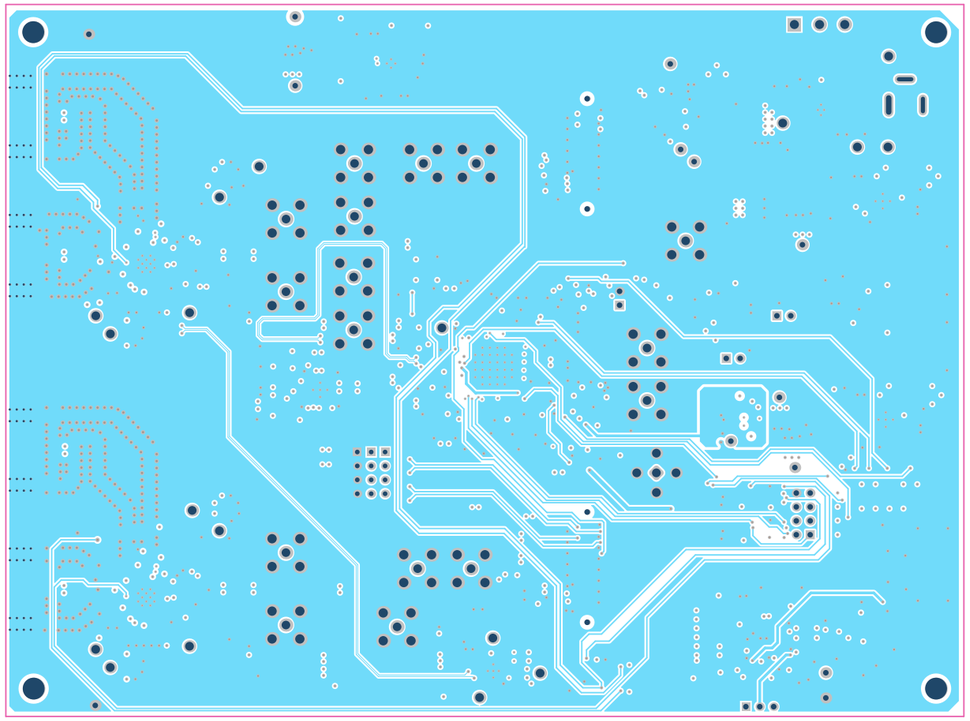
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = TOP SOLDER	TID #:01021		
PLOT NAME = Top Solder Mask	GENERATED : 10/13/2017 5:38:48 PM		TEXAS INSTRUMENTS



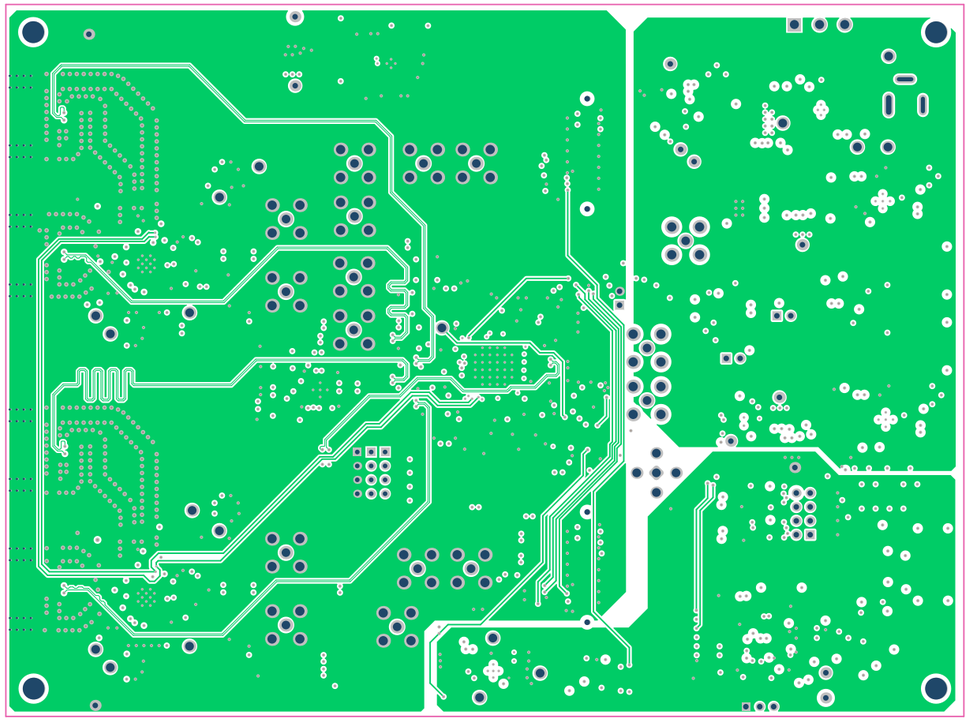
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:	
LAYER NAME = TOP LAYER	TID #:01021			
PLOT NAME = Top Layer	GENERATED : 10/13/2017 5:38:49 PM			TEXAS INSTRUMENTS



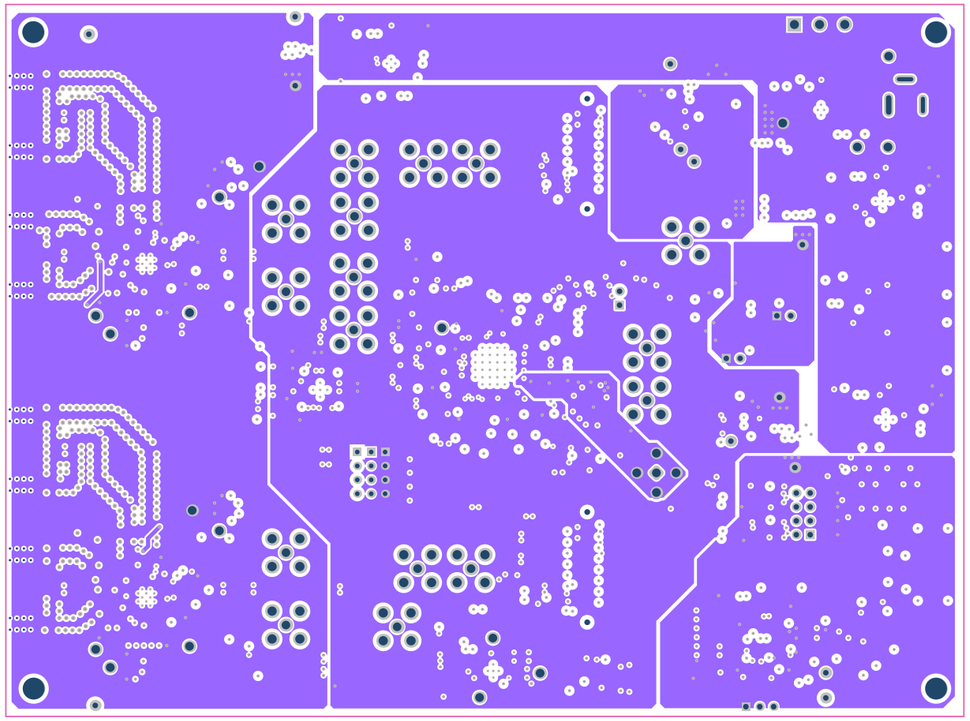
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = GND Layer	TID #:01021		
PLOT NAME = GND LAYER	GENERATED : 10/13/2017 5:38:50 PM		TEXAS INSTRUMENTS



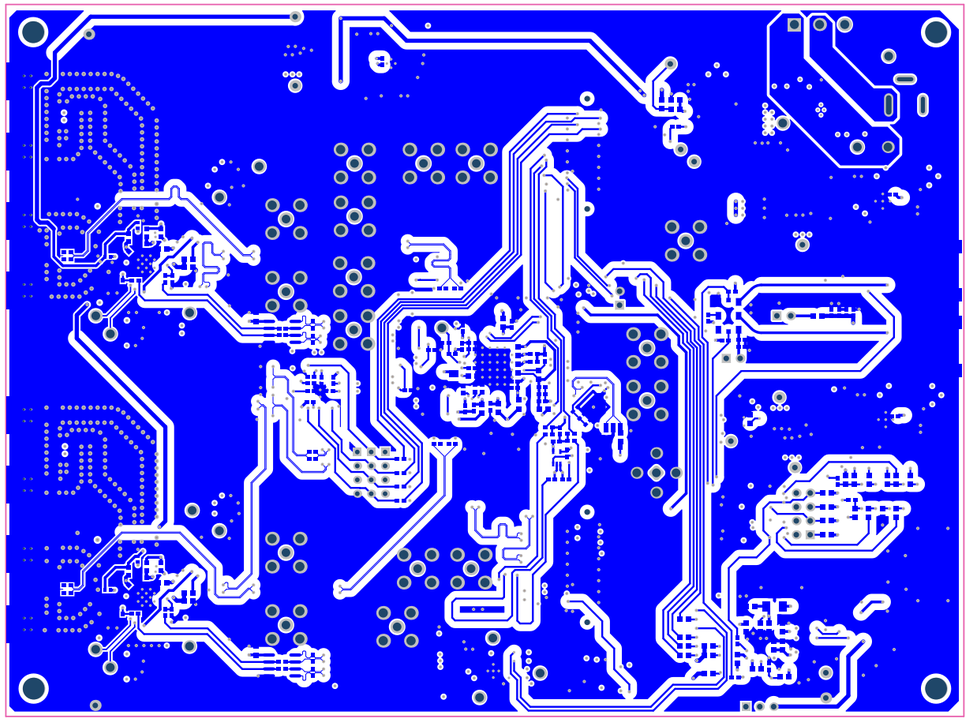
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = Signal Layer2	TID #:01021		
PLOT NAME = Signal Layer 2	GENERATED : 10/13/2017 5:38:51 PM		TEXAS INSTRUMENTS



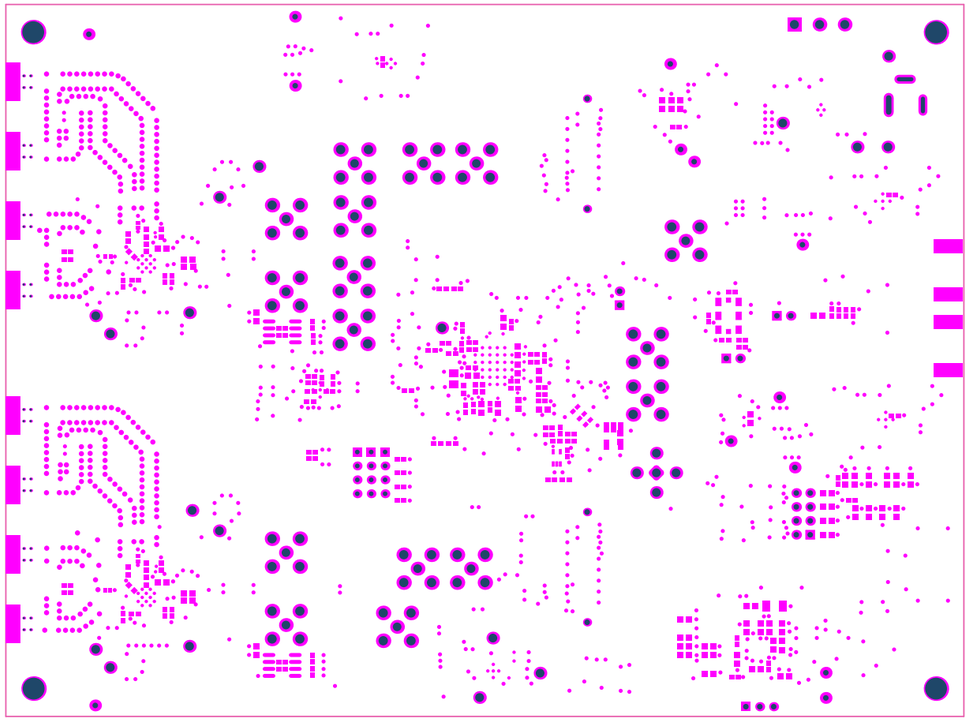
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = Signal Layer1	TID #:01021		
PLOT NAME = Signal Layer 3	GENERATED : 10/13/2017 5:38:52 PM		TEXAS INSTRUMENTS



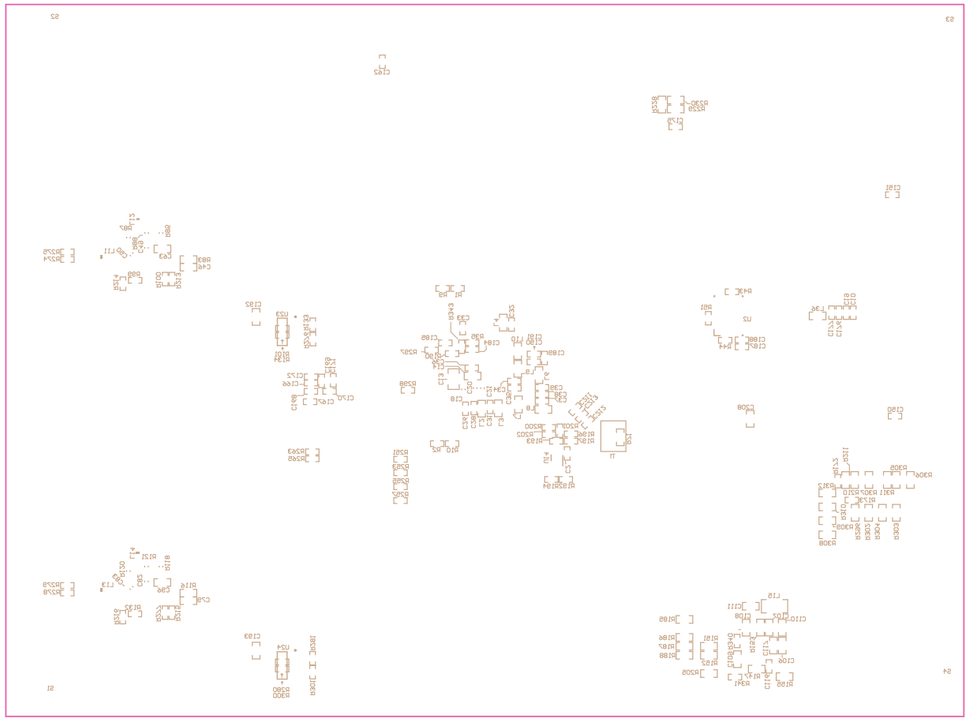
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = PWR Layer	TID #:01021		
PLOT NAME = PWR LAYER	GENERATED : 10/13/2017 5:38:53 PM		TEXAS INSTRUMENTS



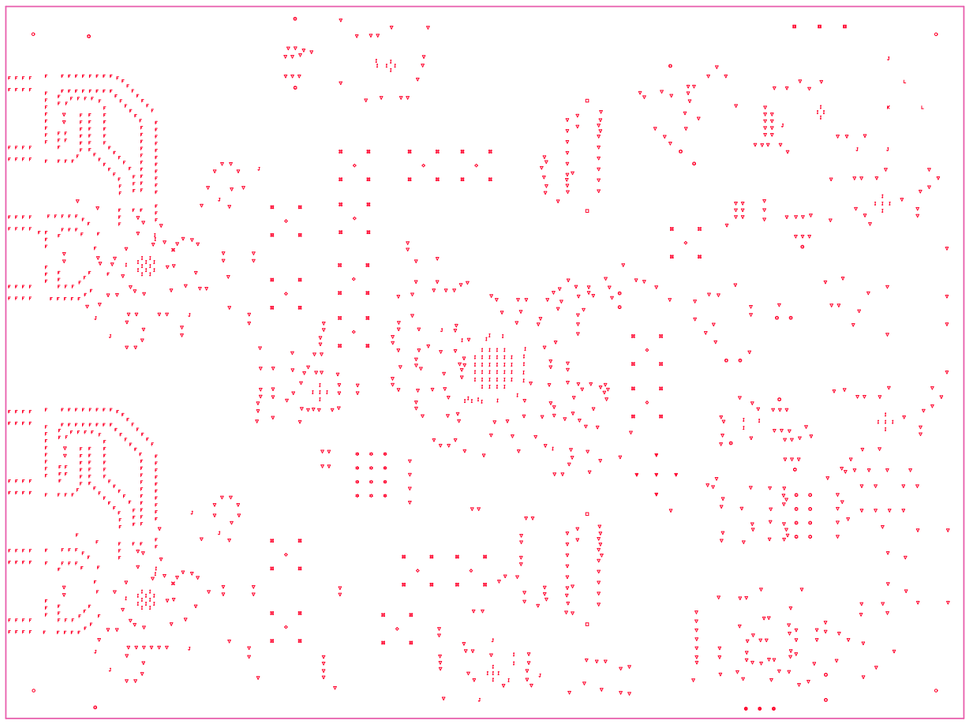
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:
LAYER NAME = BOTTOM LAYER	TID #:01021		
PLOT NAME = Bottom Layer	GENERATED : 10/13/2017 5:38:54 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SVN REV:	
LAYER NAME = BOTTOM SOLDER	TID #:01021			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/13/2017 5:38:55 PM			TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SUN REV:
LAYER NAME = BOTTOM OVERLAY	TID #:01021		
PLOT NAME = Bottom Overlay	GENERATED : 10/13/2017 5:38:56 PM		TEXAS INSTRUMENTS



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	Rogers4003C	12.00mil	4.2	
5	GND Layer	Copper	0.70mil		
6	Dielectric 4	FR4 370	8.50mil	4.2	
7	Signal Layer 1	Copper	1.40mil		
8	Dielectric 3	FR4 370	14.50mil	4.2	
9	Signal Layer 2	Copper	1.40mil		
10	Dielectric 5	FR4 370	8.50mil	4.2	
11	PWR Layer	Copper	0.70mil		
12	Dielectric 2	FR4 370	8.00mil	4.2	
13	Bottom Layer	Copper	1.40mil		
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				

IMPEDANCE TABLE:-

Layer	SE IMP (OHM) +/-10%	SE TRACE WIDTH IN MILS	DIFF IMP (OHM) +/-10%	DIFF TRACE WIDTH/SPACING IN MILS	DIFF IMP (OHM) +/-10%	WIDTH/SPACING IN MILS	REFERENCE Layer
Top Layer	50(CPW) 50	22mil 24mil	90 ohms	15mil trace/ 7mil space	100 ohms	12mil trace/ 8mil space	GND Layer
SIGNAL Layer1	50	10.5 mil	90 ohms	-	100 ohms	5.5mil trace/ 6mil space	GND Layer
SIGNAL Layer2	50	10.5 mil	90 ohms	-	100 ohms	5.5mil trace/ 6mil space	PWR Layer
BOTTOM Layer	50	13.5 mil	90 ohms	-	100 ohms	4.25mil trace/ 4.25mil space	PWR Layer

22 mil (CPW) width on top layer should be controlled 50 ohms +/- 5%
ALL SMA CONNECTORS TO FLUSH TO THE EDGE OF THE BOARD, NO GAP ALLOWED.
This is especially critical for: RFoutAP, RFoutAM, RFoutBP, and RFoutBM SMA connectors

Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad	Hole Length
I	115	7.87mil (0.200mm)	PTH	Round	Via	-
⊠	2	10.00mil (0.254mm)	PTH	Round	Via	-
▽	685	12.00mil (0.305mm)	PTH	Round	Via	-
F	375	16.00mil (0.406mm)	PTH	Round	(Mixed)	-
L	2	29.92mil (0.760mm)	PTH	Slot	Pad	120.08mil (3.050mm)
☼	12	33.46mil (0.850mm)	PTH	Round	Pad	-
K	1	39.76mil (1.010mm)	PTH	Slot	Pad	140.16mil (3.560mm)
⌬	27	40.00mil (1.016mm)	PTH	Round	Pad	-
□	4	40.16mil (1.020mm)	NPTH	Round	Pad	-
⊕	3	40.16mil (1.020mm)	PTH	Round	Pad	-
◇	16	62.00mil (1.575mm)	PTH	Round	Pad	-
▼	5	62.99mil (1.600mm)	PTH	Round	Pad	-
J	18	63.00mil (1.600mm)	PTH	Round	Pad	-
▣	3	64.96mil (1.650mm)	PTH	Round	Pad	-
⊠	64	67.00mil (1.702mm)	PTH	Round	Pad	-
○	4	157.00mil (3.988mm)	NPTH	Round	Pad	-
	1336 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table
FOR 7.874MIL DRILL +0/-7.874MIL
FOR 10MIL DRILL +0/-10MIL
FOR 12MIL DRILL +0/-12MIL
FOR 16MIL DRILL +0/-16MIL
FOR PTH DRILL +/-3MIL
FOR NPTH DRILL +/-2MIL

DESIGN INFORMATION

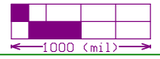
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
175MM X 130mm
Number of Layers : 6
MIN. TRACK WIDTH: 4.25 MIL
MIN. CLEARANCE: 4.25 MIL
MIN. VIA PAD SIZE: 16 MIL
MINIMUM ANNULAR RING 5.90 MIL EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [ ] FR-4 High Tg [X] OTHER Rogers4003C and FR4 370
THICKNESS: [X] 63 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [X] 0.7MIL (1/2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[ ] GREEN [X] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS: VIA TENTING: YES [ ] NO [X]
MICROSECTION: [ ] YES IMPEDANCE CONTROL: YES [X] NO [ ]
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

TEXAS INSTRUMENTS

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SUN REV:
LAYER NAME = DRILL DRAWING	TID #:01021		
PLOT NAME = Drill Drawing	GENERATED : 10/13/2017 5:38:58 PM		TEXAS INSTRUMENTS

TIDA-01021
DESIGNED FOR: Public Release
FILE NAME: TIDA-01021_E2.PcbDoc
ENGINEER: Ajeet Pal
LAYOUT BY: Avinash N
SCALE: 0.92
ALTIUM DESIGNER VERSION: 16.1.9.221



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01021	REV: E2	SUN REV:
LAYER NAME =	TID #:01021		
PLOT NAME = Board Dimensions	GENERATED : 10/13/2017 5:39:01 PM		TEXAS INSTRUMENTS

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